



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

TZ-CHENG CHIU

Serial No. 10/631,130 (TI-35061)

Filed July 31, 2003

For: COMPOSITE LID FOR LAND GRIP ARRAY  
(LGA) FLIP CHIP PACKAGE ASSEMBLY

Art Unit 2825

Examiner Calvin Lee

Customer No. 23494

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3-26-04

Jay M. Cantor, Reg. No. 19,906

**ELECTION**

Sir:

Responsive to the Office action dated march 15, 2004, applicant elects the invention listed as (1) and including claims 1 to 10 without traverse.

Claims 11 to 24 are retained pending filing of a divisional application therefore.

Action and allowance are respectfully requested.

Respectfully submitted,

Jay M. Cantor

Attorney for Applicant(s)

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